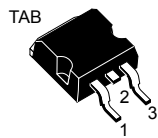
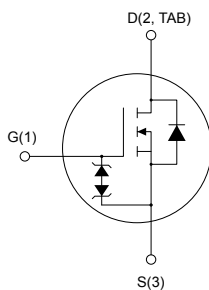


N-channel 900 V, 210 mΩ typ., 20 A MDmesh K5 Power MOSFET in a D²PAK package


D²PAK


AM01476v1_tab


Product status link
[STB20N90K5](#)
Product summary

Order code	STB20N90K5
Marking	20N90K5
Package	D ² PAK
Packing	Tape and reel

Features

Order code	V _{DS}	R _{DS(on)} max.	I _D
STB20N90K5	900 V	250 mΩ	20 A

- Very low FoM (figure of merit)
- Ultra-low gate charge
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

This very high voltage N-channel Power MOSFET is designed using MDmesh K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 30	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	20	A
I_D	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	13	A
$I_{DM}^{(1)}$	Drain current (pulsed)	80	A
P_{TOT}	Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$	250	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	4.5	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	
T_J	Operating junction temperature range	-55 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature range		

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 20\text{ A}$, $di/dt \leq 100\text{ A}/\mu\text{s}$; $V_{DS\text{ peak}} \leq V_{(BR)DSS}$, $V_{DD} = 450\text{ V}$.
3. $V_{DS} \leq 720\text{ V}$.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance, junction-to-case	0.5	$^\circ\text{C}/\text{W}$
$R_{thJA}^{(1)}$	Thermal resistance, junction-to-ambient	30	$^\circ\text{C}/\text{W}$

1. When mounted on a standard 1 inch² area of FR-4 PCB with 2-oz copper.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T_J max.)	6.5	A
E_{AS}	Single pulse avalanche energy (starting $T_J = 25\text{ }^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	500	mJ

2 Electrical characteristics

$T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Table 4. On/off-state

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	900			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 900\text{ V}$			1	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 900\text{ V}$			50	μA
		$T_C = 125\text{ }^{\circ}\text{C}$ ⁽¹⁾				
I_{GSS}	Gate body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$			± 10	μA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 100\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 10\text{ A}$		210	250	m Ω

1. Specified by design, not tested in production.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	1500	-	pF
C_{oss}	Output capacitance		-	120	-	pF
C_{rss}	Reverse transfer capacitance		-	1	-	pF
$C_{o(er)}$ ⁽¹⁾	Equivalent capacitance energy related	$V_{GS} = 0\text{ V}$, $V_{DS} = 0\text{ to }720\text{ V}$	-	78	-	pF
$C_{o(tr)}$ ⁽²⁾	Equivalent capacitance time related			220	-	pF
R_g	Intrinsic gate resistance	$f = 1\text{ MHz}$, $I_D = 0\text{ A}$	-	3.7	-	Ω
Q_g	Total gate charge	$V_{DD} = 720\text{ V}$, $I_D = 20\text{ A}$	-	40	-	nC
Q_{gs}	Gate-source charge	$V_{GS} = 0\text{ to }10\text{ V}$	-	14	-	nC
Q_{gd}	Gate-drain charge	(see Figure 14. Test circuit for gate charge behavior)	-	17	-	nC

1. $C_{o(er)}$ is a constant capacitance value that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

2. $C_{o(tr)}$ is a constant capacitance value that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 450\text{ V}$, $I_D = 10\text{ A}$, $R_G = 4.7\text{ }\Omega$	-	20.2	-	ns
t_r	Rise time		-	13.5	-	ns
$t_{d(off)}$	Turn-off delay time	$V_{GS} = 10\text{ V}$ (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	64.7	-	ns
t_f	Fall time		-	16	-	ns

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		20	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		80	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 20\text{ A}$, $V_{GS} = 0\text{ V}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 20\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	517		ns
Q_{rr}	Reverse recovery charge		-	11.4		μC
I_{RRM}	Reverse recovery current		-	44		A
t_{rr}	Reverse recovery time	$I_{SD} = 20\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 60\text{ V}$, $T_J = 150\text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	674		ns
Q_{rr}	Reverse recovery charge		-	14		μC
I_{RRM}	Reverse recovery current		-	41.6		A

1. Pulse width limited by safe operating area

2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

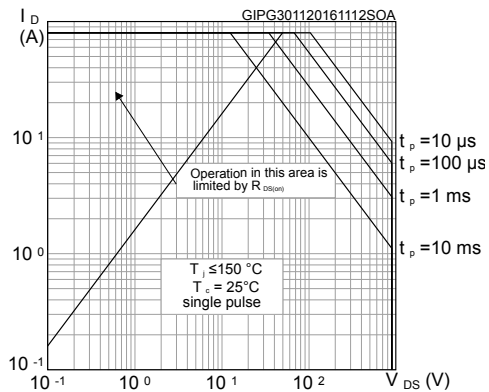
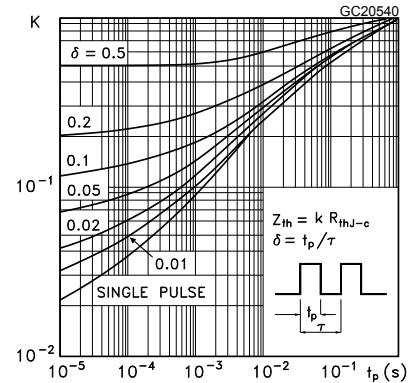
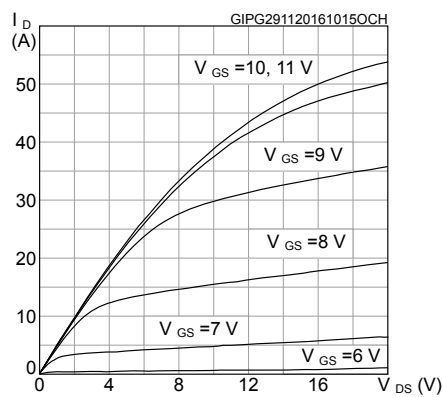
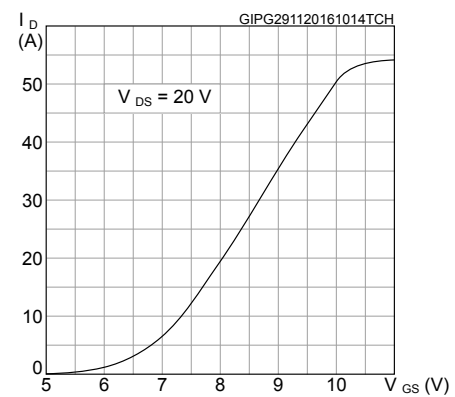
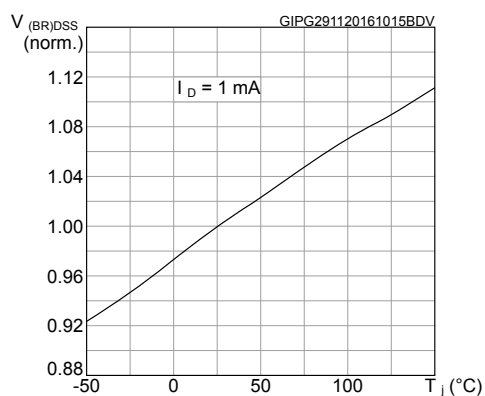
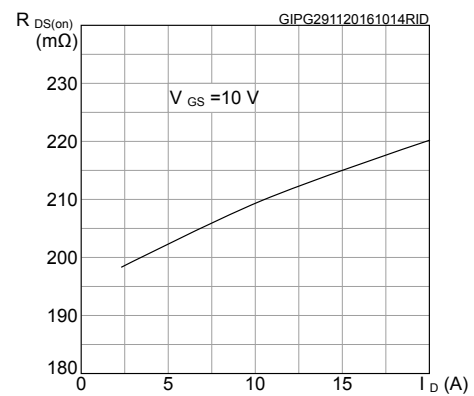
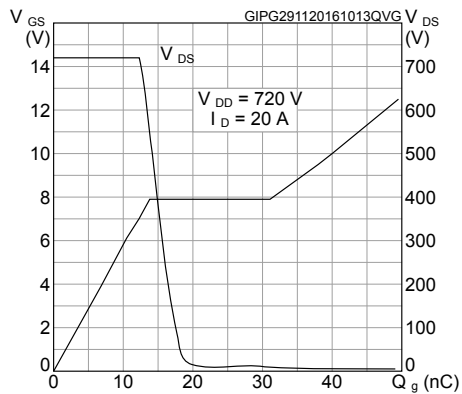
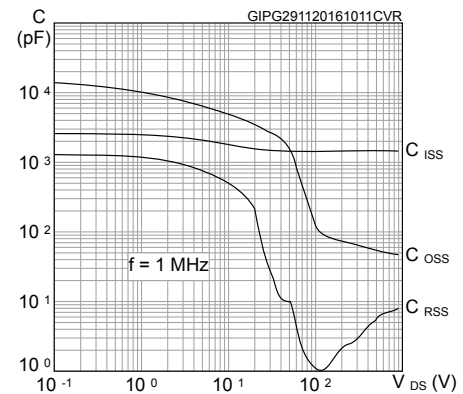
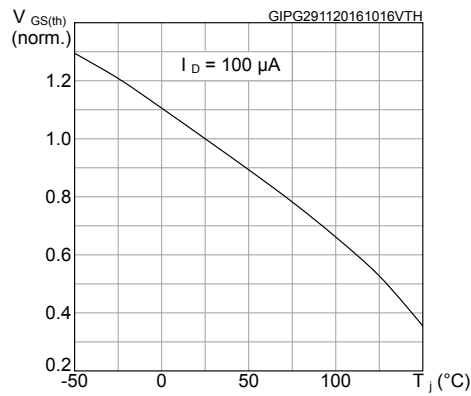
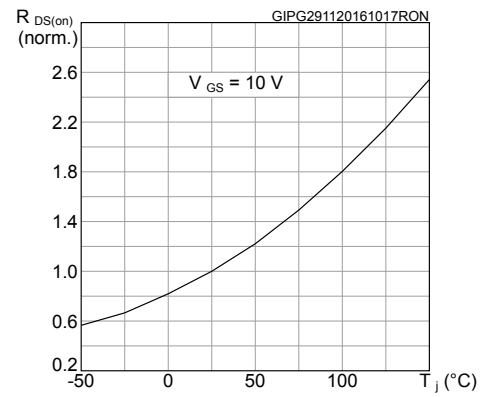
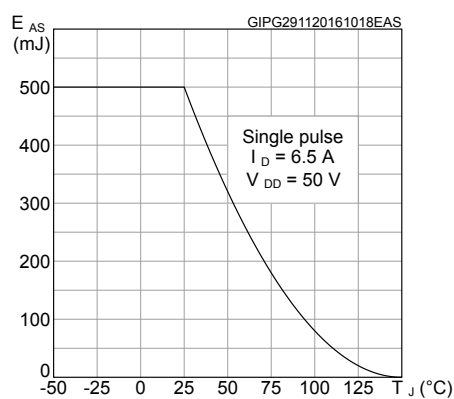
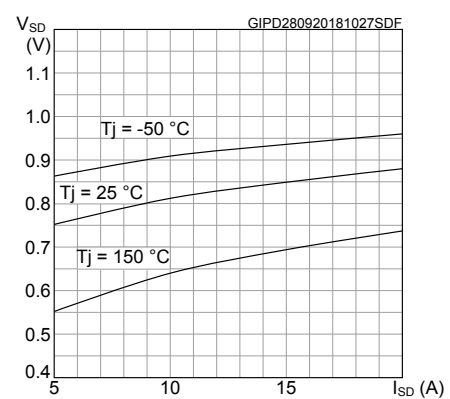
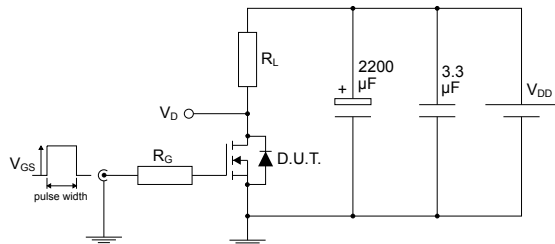
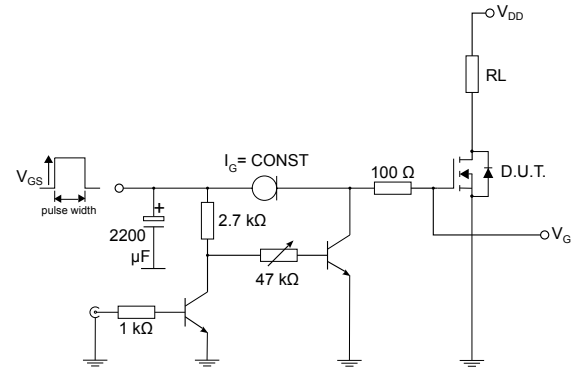
Figure 1. Safe operating area

Figure 2. Thermal impedance

Figure 3. Output characteristics

Figure 4. Transfer characteristics

Figure 5. Normalized $V_{(BR)DSS}$ vs temperature

Figure 6. Static drain-source on-resistance


Figure 7. Gate charge vs gate-source voltage

Figure 8. Capacitance variation

Figure 9. Normalized gate threshold voltage vs temperature

Figure 10. Normalized on-resistance vs temperature

Figure 11. Maximum avalanche energy vs. starting T_J

Figure 12. Source-drain diode forward characteristics


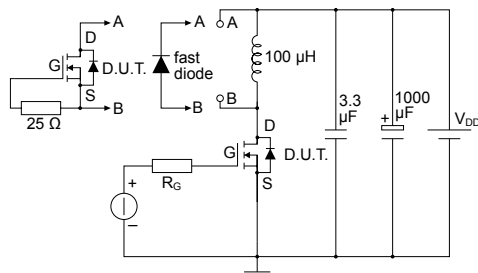
3 Test circuits

Figure 13. Test circuit for resistive load switching times


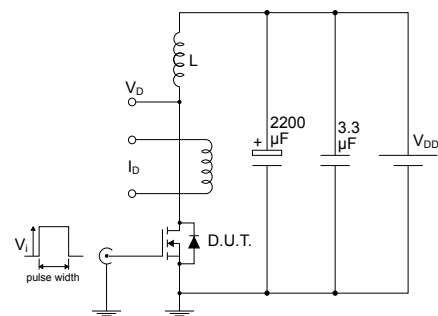
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Figure 14. Test circuit for gate charge behavior


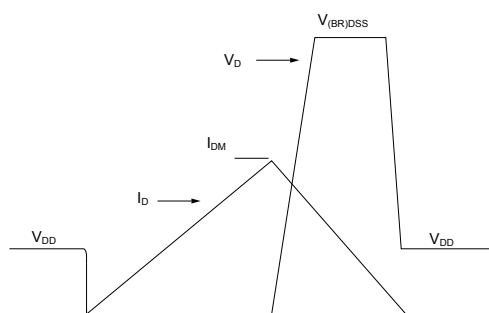
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Figure 15. Test circuit for inductive load switching and diode recovery times


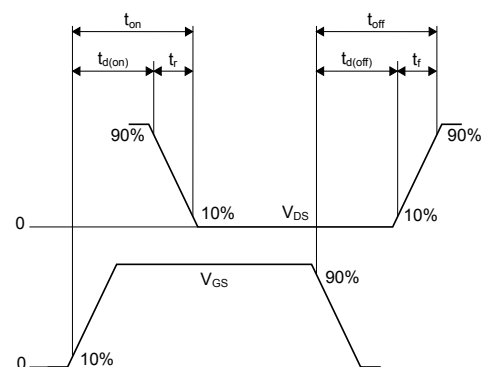
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Figure 16. Unclamped inductive load test circuit


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Figure 17. Unclamped inductive waveform


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Figure 18. Switching time waveform


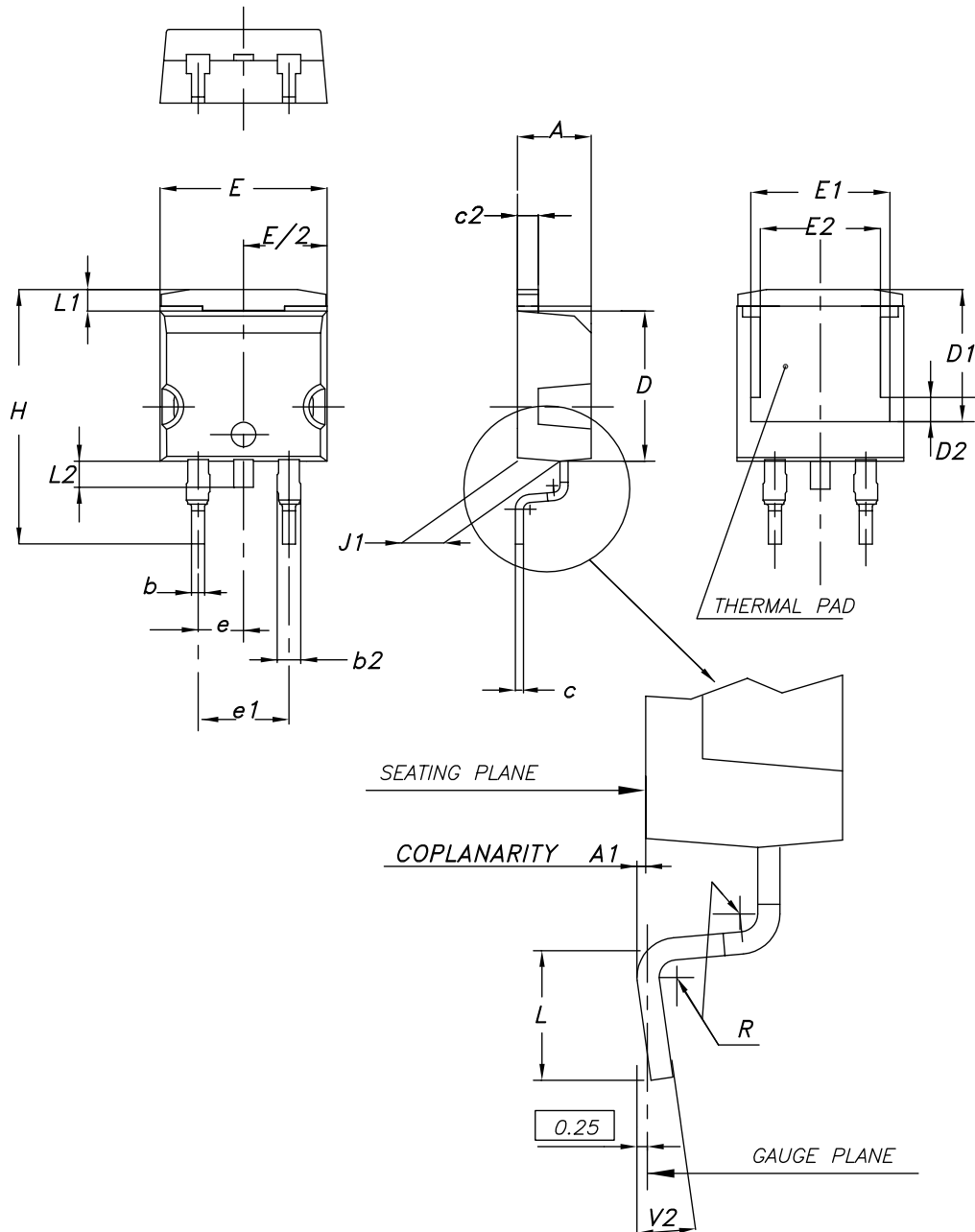
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4 Package information

To meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 D²PAK (TO-263) type A2 package information

Figure 19. D²PAK (TO-263) type A2 package outline

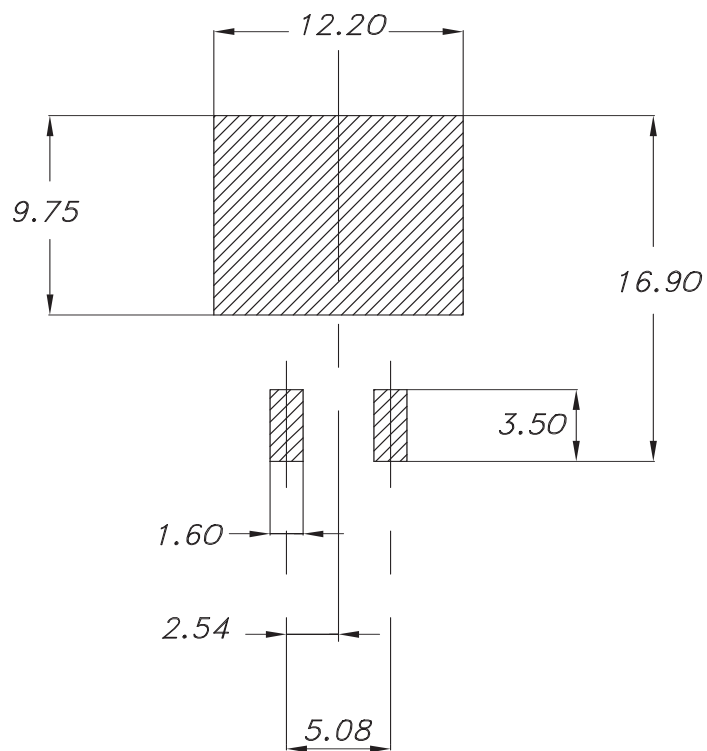


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Table 8. D²PAK (TO-263) type A2 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.70	8.90	9.10
E2	7.30	7.50	7.70
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

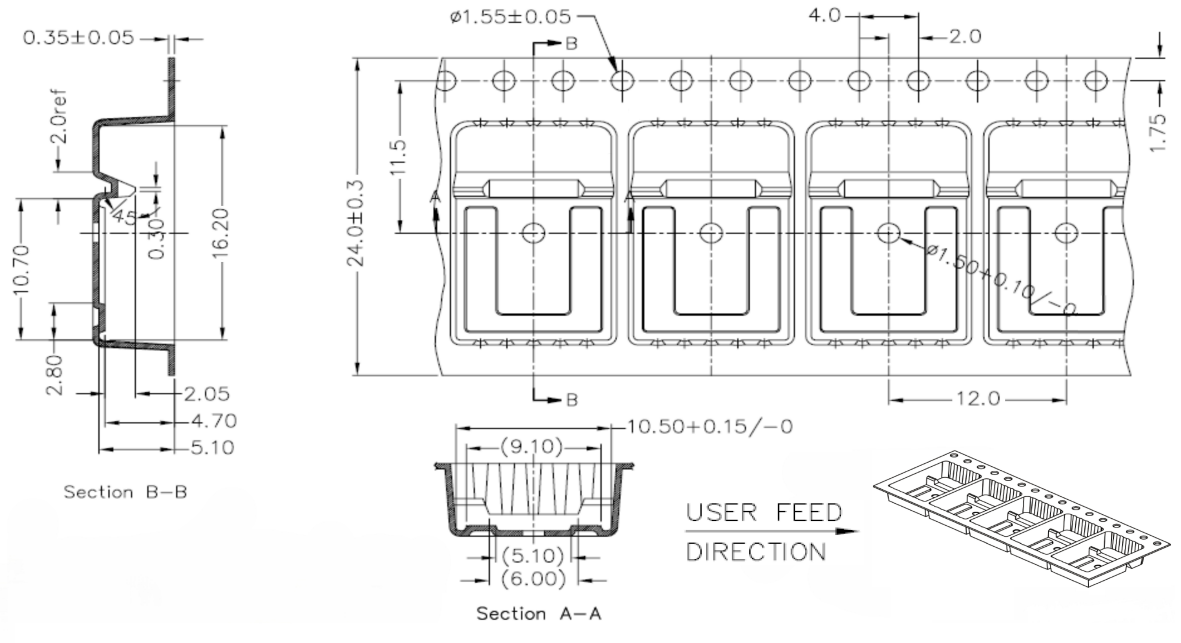
Figure 20. D²PAK (TO-263) recommended footprint (dimensions are in mm)



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4.2 D²PAK packing information

Figure 21. D²PAK tape drawing (dimensions are in mm)



DM01095771_2

Revision history

Table 9. Document revision history

Date	Revision	Changes
19-May-2016	1	First release.
01-Dec-2016	2	Modified title and $R_{DS(on)}$ in features table Modified <i>Table 4: "Avalanche characteristics"</i> , <i>Table 5: "On/off-state"</i> , <i>Table 6: "Dynamic"</i> , <i>Table 7: "Switching times"</i> , <i>Table 8: "Source-drain diode"</i> Added <i>Section 2.1: "Electrical characteristics (curves)"</i> Modified <i>Section 3: "Test circuits"</i> Datasheet promoted from preliminary data to production data Minor text changes
24-Jan-2017	3	Modified <i>Table 7: "Switching times"</i> . Minor text changes.
04-Oct-2018	4	Removed maturity status indication from cover page. Added <i>Figure 12. Source-drain diode forward characteristics</i> . Minor text changes.
21-Aug-2025	5	Updated Section 4: Package information . Minor text changes.

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